# imall

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## Contact us

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### QED422, QED423 Plastic Infrared Light Emitting Diode

### Features

- λ= 880 nm
- Chip material = AlGaAs
- Package type: Plastic TO-46
- Matched Photosensor: QSD722/723/724
- Medium Wide Emission Angle, 30°
- High Output Power
- Package material and color: clear, purple tinted, plastic

### **Package Dimensions**

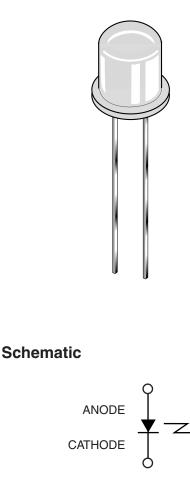
### 0.190 (4.83) 0.178 (4.52) REFERENCE SURFACE 0.220 (5.59) 0.030 (0.76) NOM 0.800 (20.3) MIN 0.050 (1.27) CATHODE 0.100 (2.54) NOM Ø 0.215 (5.46) NOM 0.020 (0.51) 45 SQ. (2X) R 0.022 (0.56)

### NOTES:

- 1. Dimensions for all drawings are in inches (mm).
- 2. Tolerance of  $\pm$  .010 (.25) on all non-nominal dimensions unless otherwise specified.



The QED422/423 is an 880 nm AlGaAs LED encapsulated in a clear, purple tinted, plastic TO-46 package.



### **Absolute Maximum Ratings** (T<sub>A</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Rating	Unit
Operating Temperature	T <sub>OPR</sub>	-40 to + 100	°C
Storage Temperature	T <sub>STG</sub>	-40 to + 100	°C
Soldering Temperature (Iron) <sup>(2,3,4)</sup>	T <sub>SOL-I</sub>	240 for 5 sec	°C
Soldering Temperature (Flow) <sup>(2,3)</sup>	T <sub>SOL-F</sub>	260 for 10 sec	°C
Continuous Forward Current	١ <sub>F</sub>	100	mA
Reverse Voltage	V <sub>R</sub>	5	V
Power Dissipation <sup>(1)</sup>	PD	200	mW

#### Notes:

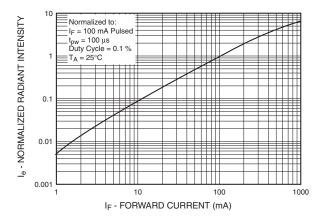
- 1. Derate power dissipation linearly 2.67 mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron 1/16" (1.6 mm) minimum from housing

### **Electrical/Optical Characteristics** (T<sub>A</sub> =25°C)

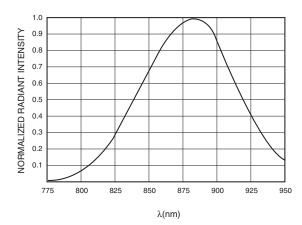
Parameter Test Conditions		Symbol	Min	Тур	Max	Units
Peak Emission Wavelength	I <sub>F</sub> = 100 mA	λ <sub>PE</sub>	_	880	_	nm
Emission Angle	l <sub>F</sub> = 100 mA	201/2	—	30	_	Deg.
Forward Voltage	I <sub>F</sub> = 100 mA, tp = 20 ms	V <sub>F</sub>	_	_	1.8	V
Reverse Current	V <sub>R</sub> = 5 V	I <sub>R</sub>	—	_	10	μA
Radiant Intensity QEC422	I <sub>F</sub> = 100 mA, tp = 20 ms	Ι <sub>Ε</sub>	10	_	40	mW/sr
Radiant Intensity QEC423	I <sub>F</sub> = 100 mA, tp = 20 ms	Ι <sub>Ε</sub>	20	—	—	mW/sr
Rise Time	I <sub>F</sub> = 100 mA	t <sub>r</sub>	—	800	—	ns
Fall Time		t <sub>f</sub>	—	800	—	ns

#### Fig. 1 Normalized Radiant Intensity vs. Forward Current

### Fig. 2 Forward Voltage vs. Ambient Temperature







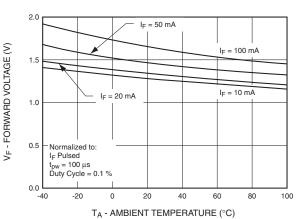
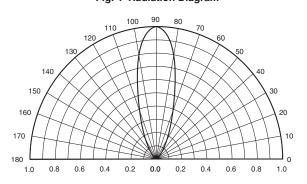


Fig. 4 Radiation Diagram



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